

Features

- Formerly **FullTec** brand
- Extremely high speed performance
- Blocks high voltages and currents
- Very high bandwidth; GHz compatible
- Small package, minimal PCB area
- Simple, superior circuit protection
- RoHS compliant*, UL Recognized **51**[®]

Applications

- Combo voice / xDSL linecards
- Voice linecards
- MDF, primary protection modules
- Process control equipment
- Test and measurement equipment
- General electronics

TBU™ C650 and C850 Protectors

Transient Blocking Units - TBU™ Devices

Bourns® C650 and C850 series TBU™ devices are high speed surge protection components designed to protect against faults caused by short circuits, AC power cross, induction and lightning surges.

The TBU™ protector blocks surges and provides an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during surge events.

Agency Approval

UL recognized component File # E315805.

Industry Standards

	Model		
Telcordia	GR-1089	Port Type 1, 3, 5	C650 C850
	GR-974	C650 C850	
ITU-T	K.20, K.20E, K.21, K	C850	

Absolute Maximum Ratings (T_{amb} = 25 °C)

Symbol	Parameter	Value	Unit	
V _{imp}	Maximum protection voltage for impulse faults with rise time \geq 1 μ sec	650 850	V	
V _{rms}	Maximum protection voltage for continuous V _{rms} faults	C650-xxx-WH C850-xxx-WH	300 425	V
T _{op}	Operating temperature range	-40 to +85	°C	
T _{stg}	Storage temperature range	-65 to +150	°C	

Electrical Characteristics (T_{amb} = 25 °C)

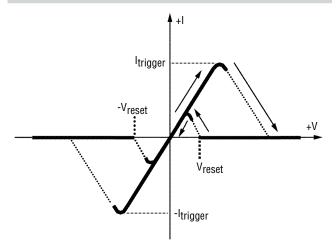
Symbol	Parameter		Min.	Тур.	Max.	Unit
I _{op}	Maximum current through the device that will not cause current blocking	Cx50-100-WH Cx50-180-WH Cx50-260-WH			100 180 260	mA
I _{trigger}	Typical current for the device to go from normal operating state to protected state	Cx50-100-WH Cx50-180-WH Cx50-260-WH		150 220 330		mA
l _{out}	Maximum current through the device	Cx50-100-WH Cx50-180-WH Cx50-260-WH			200 360 520	mA
R _{TBU}	Series resistance of the TBU™ device	C650-100-WH C650-180-WH C650-260-WH C850-100-WH C850-180-WH C850-260-WH		12 8 8 17 11	14.5 10 10 19 14 14	Ω
t _{block}	Maximum time for the device to go from normal operating state to protected state			1	μs	
Iquiescent	Current through the triggered TBU™ device with 50 Vdc circle voltage		1		mA	
V _{reset}	Voltage below which the triggered TBU™ device will transition normal operating state	n to		14		V

C650 and C850 TBU™ protectors are bidirectional; specifications are valid in both directions.

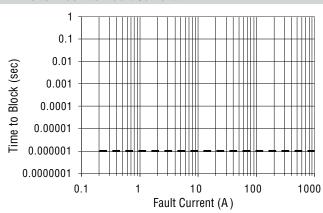
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Typical Performance Characteristics

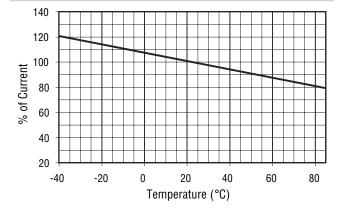
V-I Characteristics



Time to Block vs. Fault Current



Current vs. Temperature



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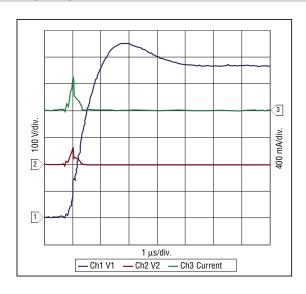
Operational Characteristics

The graphs below demonstrate the operational characteristics of the TBU[™] protector. For each graph the fault voltage, protected side voltage, and current is presented.

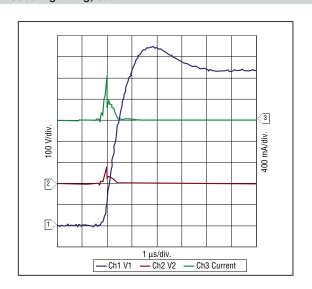
TEST CONFIGURATION DIAGRAM



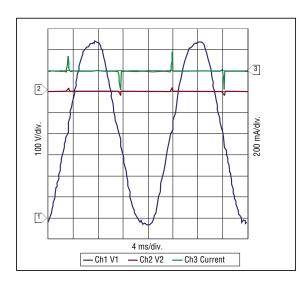
C650 Lightning, 650 V



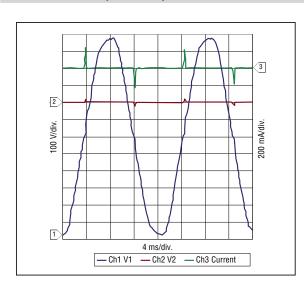
C850 Lightning, 850 V



C650 Power Fault, 300 Vrms, 100 A

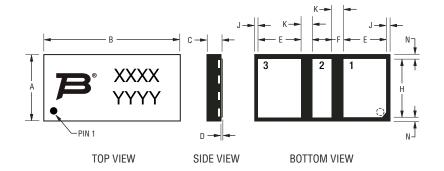


C850 Power Fault, 425 Vrms, 100 A



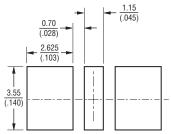
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Product Dimensions



Dim.	Min.	Тур.	Max.
А	3.90	4.00	4.10
	(.154)	(.157)	(.161)
В	8.15	8.25	8.35
	(.321)	(.325)	(.329)
С	0.80	0.85	0.90
	(.031)	(.033)	(.035)
D	0.000 (.000)	<u>0.025</u> (.001)	0.050 (.002)
Е	2.55	2.60	2.65
	(.100)	(.102)	(.104)
F	1.10	1.15	1.20
	(.043)	(.045)	(.047)
Н	3.45	3.50	3.55
	(.136)	(.138)	(.140)
٦	<u>0.20</u>	<u>0.25</u>	<u>0.30</u>
	(.008)	(.010)	(.012)
К	<u>0.65</u>	<u>0.70</u>	<u>0.75</u>
	(.026)	(.028)	(.030)
N	<u>0.20</u>	<u>0.25</u>	<u>0.30</u>
	(.008)	(.010)	(.012)

Recommended Pad Layout



rau Designation							
Pad #	Apply						
1	In/Out						
2	NC						
3	In/Out						

NC = Solder to PCB; do not make electrical connection, do not connect to ground.

DIMENSIONS: $\frac{MM}{(INCHES)}$

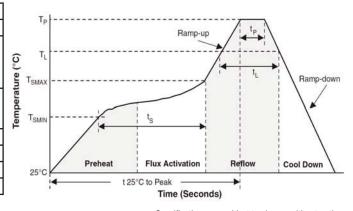
TBUTM protectors have matte-tin termination finish. Suggested layout should use non-solder mask define (NSMD). Recommended stencil thickness is 0.10-0.12 mm (.004-.005 in.) with stencil opening size 0.025 mm (.0010 in.) less than the device pad size. As when heat sinking any power device, it is recommended that, wherever possible, extra PCB copper area is allowed. For minimum parasitic capacitance, do not allow any signal, ground or power signals beneath any of the pads of the device.

Thermal Resistances

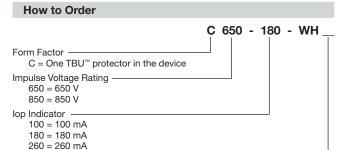
Symbol	Parameter	Value	Unit
R _{th(j-a)}	Junction to leads (package)	116	°C/W

Reflow Profile

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/sec. max.
Preheat - Temperature Min. (Tsmin) - Temperature Max. (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 sec.
Time maintained above: - Temperature (TL) - Time (tL)	217 °C 60-150 sec.
Peak/Classification Temperature (Tp)	260 °C
Time within 5 °C of Actual Peak Temp. (tp)	20-40 sec.
Ramp-Down Rate	6 °C/sec. max.
Time 25 °C to Peak Temperature	8 min. max.



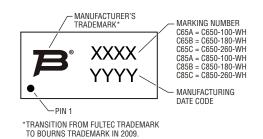
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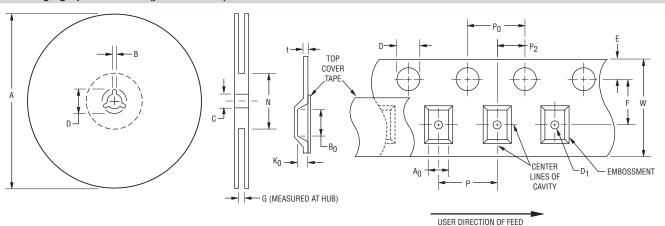
Packaging Indicator Blank = Packaged in tape and reel (3000 pieces per reel)

X = Packaged in tubes (40 pieces per tube)

Typical Part Marking



Packaging Specifications (per EIA468-B)



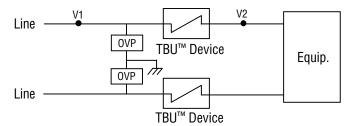
Device	АВ		3	С		D		G	N	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
C650, C850	326 (12.835)	330.25 (13.002)	1.5 (.059)	2.5 (.098)	12.8 (.504)	13.5 (.531)	20.2 (.795)	-	16.5 (.650)	102 (4.016)

Device	A ₀		В0		D		D ₁		E		F	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	max.
C650, C850	4.2 (.165)	4.4 (.173)	8.45 (.333)	8.65 (.341)	1.5 (.059)	1.6 (.063)	1.5 (.059)	-	1.65 (.065)	1.85 (.073)	7.4 (.291)	7.6 (.299)
Device	K	K ₀ P		P	P ₀		Р	2	t		W	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
C650, C850	1.1 (.043)	1.3 (.051)	7.9 (.311)	8.1 (.319)	3.9 (.159)	4.1 (.161)	1.9 (.075)	2.1 (.083)	0.25 (.010)	0.35 (.014)	15.7 (.618)	16.3 (.642)

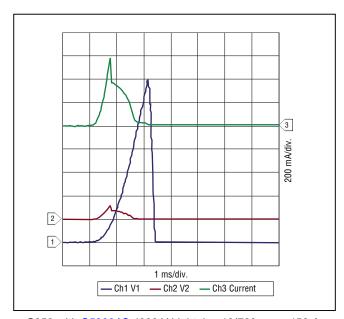
DIMENSIONS: (INCHES)

Reference Application

The C-series devices are general use protectors used in a wide variety of applications. The following diagram is one common configuration example of C-series device placement. A cost-effective protection solution combines Bourns® TBU™ protection devices with a pair of MOVs or Bourns® GDTs. The figure below demonstrates the operational characteristics of the circuit.



Common Configuration Diagram



C850 with G5200AS 4000 V Lightning 10/700 µsec, 150 A



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